LNJ836W83RA

Hight Bright Surface Mounting Chip LED

ESS Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	55	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

■ Lighting Color

Orange

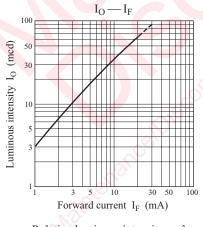
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

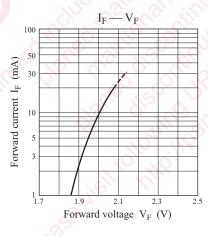
■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

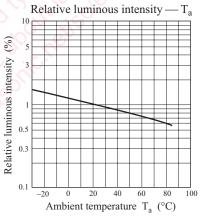
Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I_{O}	$I_F = 5 \text{ mA}$		11.5	17.5	47.3	mcd
Reverse current	I_R	$V_R = 4 V$				100	μΑ
Forward voltage	V _F	$I_F = 5 \text{ mA}$	4000		1.95	2.30	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 5 \text{ mA}$	1100 talk		630	2	nm
Dominant emission wavelength *2	$\lambda_{ m d}$	$I_F = 5 \text{ mA}$	M. Co	615	620	627	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$	60/10/10/10	76	13		nm

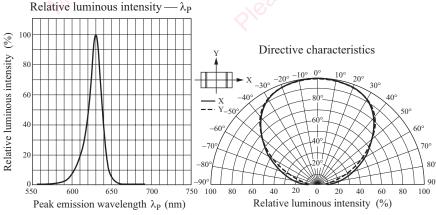
Note) *1: Measurement tolerance: ±20%

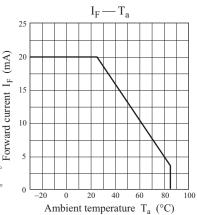
*2: Measurement tolerance: ±2 nm







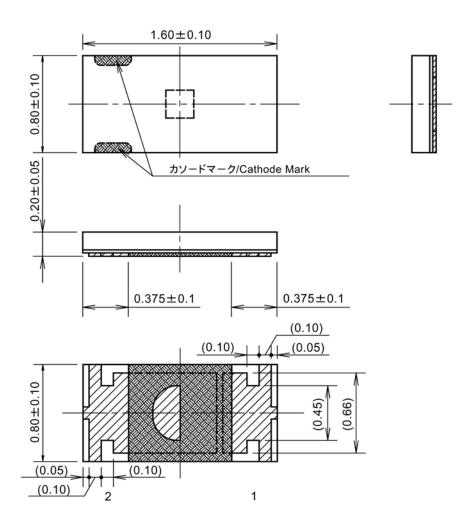




LNJ836W83RA Panasonic

■ Package (Unit: mm)

KLTFTN2K3600



- Pin name
 - 1: Anode
 - 2: Cathode

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